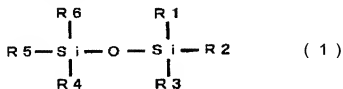


The following is a complete listing of all claims in the application, with an indication of the status of each:

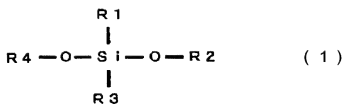
Listing of claims:

1. (Currently amended) A method of producing a porous insulating film, comprising the step of:
introducing gas containing vapor of cyclic organic silica compounds, which have silicon and oxygen skeletons and have at least one unsaturated hydrocarbon group bound with a side chain of a skeleton, and which is diluted with an inert gas, into plasma to grow a porous insulating film on a semiconductor substrate.
2. (Currently amended) A method of producing a porous insulating film, comprising the step of:
introducing vapor of cyclic organic silica compounds, which have silicon and oxygen skeletons and have at least one unsaturated hydrocarbon group bound with a side chain of a skeleton, and which is diluted with an inert gas, and vapor of straight-chain organic silica compounds, which have silicon and oxygen skeletons and have any one selected from the group consisting of hydrogen, a hydrocarbon group and a hydrocarbon oxide group bound with a side chain of a skeleton, and which is diluted with an inert gas, into plasma to grow a porous insulating film on a semiconductor substrate.
3. (Currently amended) The method of producing a porous insulating film according to claim 2, wherein said straight-chain organic silica compounds have a structure represented by the following formula (1):

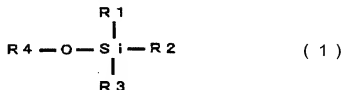
{formula 1}



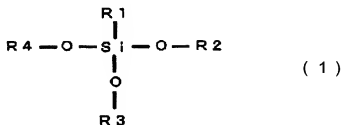
where R₁ to R₆, which may be the same or different, respectively represent any one selected from the group consisting of hydrogen, a hydrocarbon group and a hydrocarbon oxide group; or



where R₁ to R₄, which may be the same or different, respectively represent any one selected from the group consisting of hydrogen, a hydrocarbon group and a hydrocarbon oxide group; or



where R₁ to R₄, which may be the same or different, respectively represent any one selected from the group consisting of hydrogen, a hydrocarbon group and a hydrocarbon oxide group; or

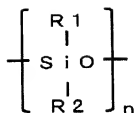


where R₁ to R₄, which may be the same or different, respectively represent any one selected from the group consisting of hydrogen, a hydrocarbon group and a hydrocarbon oxide group.

4. (Previously presented) The method of producing a porous insulating film according to claim 2, wherein a supply ratio of said cyclic organic silica compounds to said straight-chain organic silica compounds is changed during film formation.

5. (Currently amended) The method of producing a porous insulating film according to claim 1, wherein said cyclic organic silica compounds are cyclosiloxane monomers represented by the following formula (2):

[formula 2]

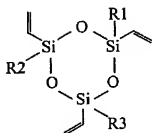


(2) Cyclosiloxane monomer

where R₁ and R₂ are respectively any one of the group consisting of hydrogen, an alkyl group, an alkoxide group, an amino group, alkene, alkyne, a phenyl group and a phenol group, provided that R₁ and R₂ may be the same or different, provided that at least one of the side chain groups is an unsaturated hydrocarbon group, and n is an integer of 2 or more.

6. (Currently amended) The method of producing a porous insulating film according to claim 5, wherein said cyclic organic silica compounds are trivinylcyclotrisiloxane derivative monomers represented by the following formula (3):

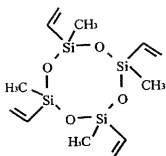
[formula 3]



(3) Trivinylcyclotrisiloxane derivative

7. (Currently amended) The method of producing a porous insulating film according to claim 5, wherein said cyclic organic silica compound is tetravinyltetramethylcyclotetrasiloxane monomers represented by the following formula (4):

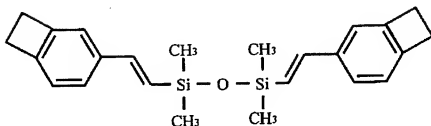
[formula 4]



(4) Tetravinyltetramethylcyclotetrasiloxane

8. (Currently amended) The method of producing a porous insulating film according to claim 2, wherein said cyclic organic silica compounds are tetravinyltetramethyl-cyclotetrasiloxane monomers represented by the formula (4) and said straight-chain organic silica compounds are divinylsiloxanebenzocyclobutene monomers represented by the following formula (5):

[formula 5]



(5) Divinylsiloxanebenzocyclobutene

9. (Previously presented) The method of producing a porous insulating film according to claim 1, wherein said plasma is plasma of rare gas.

10. (Previously presented) A semiconductor device according to claim 1, wherein said plasma is plasma of mixture gas of rare gas and oxidizer gas or hydrogenated silicon gas.

11. (Previously presented) A porous insulating film produced by the method of producing a porous insulating film according to claim 1.

12. (Original) The porous insulating film according to claim 11, comprising at least silicon, carbon, oxygen and hydrogen and having a Raman spectrum corresponding to at least three-

membered silica skeleton in the Raman spectroscopic analysis.

13. (Previously presented) The porous insulating film according to claim 11, wherein ratios of elements in the film is: O/Si = 0.8 to 1.2, C/Si = 1.5 to 10.0 and H/Si = 4.0 to 15.0.

14. (Previously presented) The porous insulating film according to claim 11, wherein the diameter of pores contained in the film is 3 nm or less.

15. (Previously presented) The porous insulating film according to claim 11, wherein at least a part of pores contained in the film have almost the same diameters as a skeleton of said cyclic organic silica compounds.

16. (Previously presented) A semiconductor device using the porous insulating film according to claim 11 as a layer insulating film of a multilayer wiring.

17. (Original) The semiconductor device according to claim 16, wherein in the vicinity of a interface between the porous insulating film and a non-porous insulating film, a relative concentration of carbon atom in at least the porous insulating film changes stepwise or continuously.

18. (Currently amended) The semiconductor device according to claim ~~17~~ 31, wherein said straight-chain organic silica compounds have a structure represented by said formula (1).

19. (Previously presented) The semiconductor device according to claim 16, wherein said cyclic organic silica compounds are cyclosiloxane monomers represented by said formula (2), where R_1 and R_2 are any one selected from the group consisting of hydrogen, an alkyl group, an alkoxide group, an amino group, alkene, alkyne, a phenyl group and a phenol group, provided that R_1 and R_2 may be the same or different, provided that at least one of side chain groups is an unsaturated hydrocarbon group, and n is an integer of 2 or more.

20. (Original) The semiconductor device according to claim 19, wherein said cyclic organic silica compounds are tetravinyltetramethylcyclotetrasiloxane monomers represented by said formula (4).
21. (Original) The semiconductor device according to claim 19, wherein said cyclic organic silica compounds are trivinylcyclotrisiloxane derivative monomers represented by said formula (3).
22. (Original) The semiconductor device according to claim 18, wherein said straight-chain organic silica compounds are divinylsiloxanebenzocyclobutene monomers represented by said formula (5).
23. (New) A porous insulating film having a distribution of pore diameter with a single peak, wherein the specific inductive capacity is equal to or greater than 2.1 and equal to or smaller than 2.7.
24. (New) The porous insulating film according to claim 23, wherein a ratio of elements in the film is $C/Si = 1.5$ to 10.0 .
25. (New) The porous insulating film according to claim 24, wherein a ratio of elements in the film is $O/Si = 0.8$ to 1.2 .
26. (New) The porous insulating film according to claim 25, wherein a ratio of elements in the film is $H/Si = 4.0$ to 15.0 .
27. (New) The porous insulating film according to claim 23, wherein a pore diameter at the maximum frequently appearance is equal to or smaller than 1 nm .
28. (New) The porous insulating film according to claim 23, comprising three membered silica.

29. (New) A semiconductor device using the porous insulating film according to claim 23 as a layer insulating film.

30. (New) A porous insulating film produced by the method of producing a porous insulating film according to claim 2.

31. (New) A semiconductor device using the porous insulating film produced by the method of claim 30.